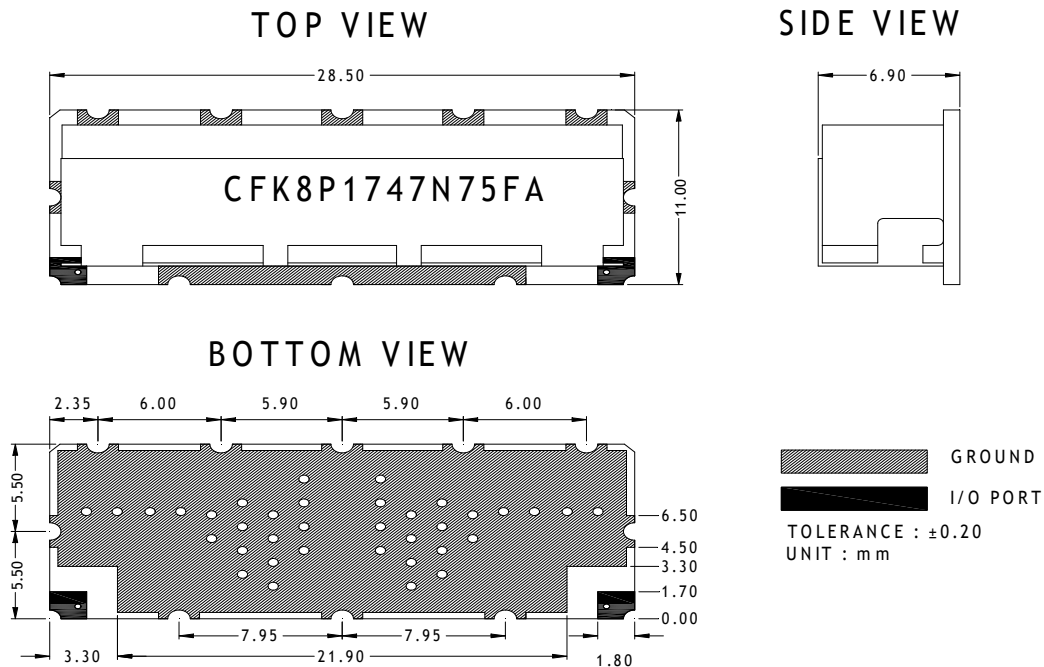


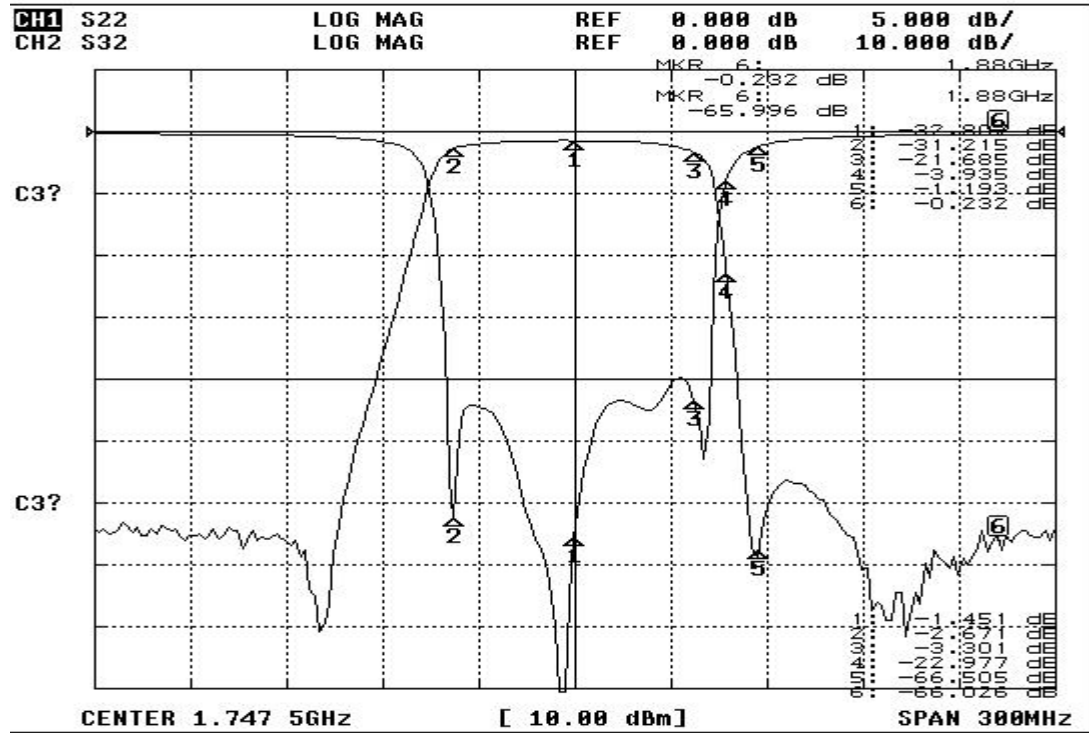
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	1747.5	MHz
Bandwidth [BW]	$f_o \pm 37.5$ [1710~1785]	MHz
Insertion Loss in BW	4.0	dB max
Ripple in BW	2.0	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	20.0 dB min @ 1795	MHz
	50.0 dB min @ 1805~1880	MHz
	dB min @ $f_o \pm [\sim]$	MHz
	dB min @ $f_o \pm [\sim]$	MHz
Group Delay Variation		ns max
Input Power	1	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

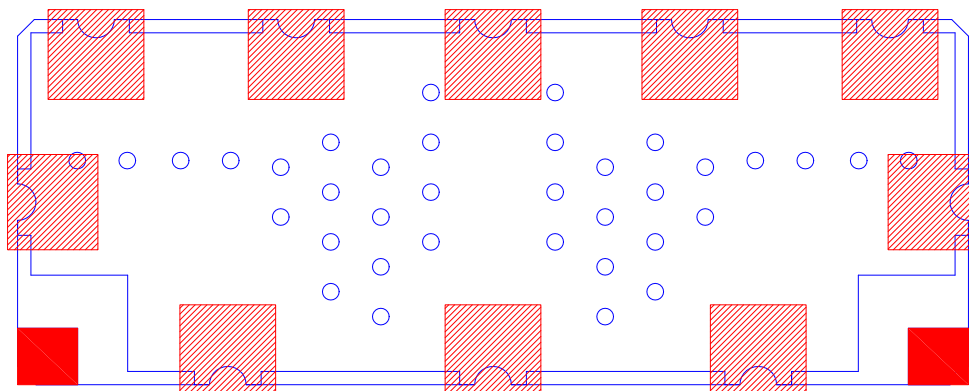
Mechanical Specification



 Plot Data



 Recommended PC Board Pattern

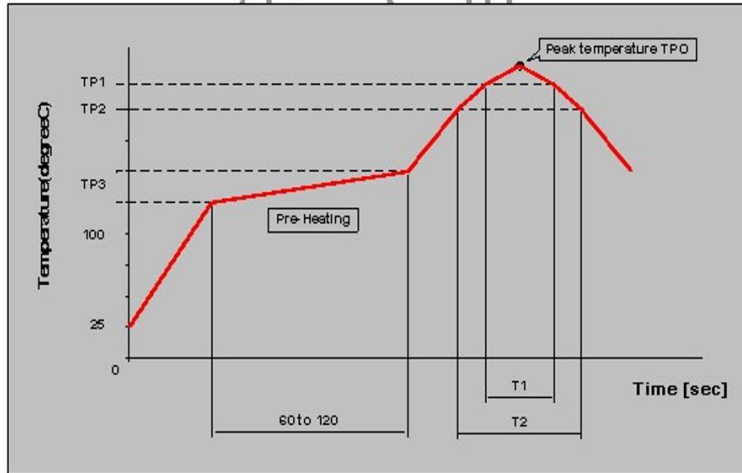


GROUND SOLDERING POINT



I/O PORT SOLDERING POINT

Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180